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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Heinen, et al.

Serial No.: 09/186,973

Filed: 11/05/98

For: WAFER-SCALE ASSEMBLY OF CHIP-SIZE PACKAGES

Docket No.: TI-23158

Examiner: Foong

Art Unit: 2823

Amendment under 37 CFR 1.116

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

6-14-02

Michael K. Skrehot
Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 03/14/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Please amend the above-referenced application as follows:

In the Claims:

Please amend the claims as follows:

14. (Twice Amended) A method for the fabrication of a semiconductor assembly comprising:

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Sub
E1

AF/2800

#16/D

ne
780

7-15-02

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